Abstracts

Three-Dimensional MMIC Technology for Multifunction Integration and its Possible Application to Masterslice MMIC

T. Tokumitsu, K. Nishikawa, K. Kamogawa, I. Toyoda and M. Aikawa. "Three-Dimensional MMIC Technology for Multifunction Integration and its Possible Application to Masterslice MMIC." 1996 Microwave and Millimeter-Wave Monolithic Circuits Symposium Digest 98. (1996 [MCS]): 85-88.

We first verified that the integration level of multifunction MMIC's can be easily increased three-fold by using three-dimensional (3-D) MMIC structure, in comparison to planar ones. The technology was used to build high-density masterslice MMIC's on a single footprint in 2 x 2 mm by incorporating two levels of ground metals in the 3-D structure.

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